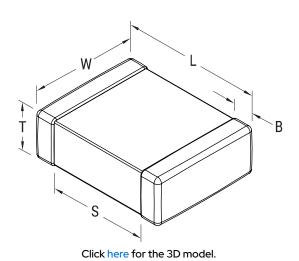


C0603X131G2TACTU

Aliases (C0603X131G2TAC7867) SMD Comm X8G HT150C Flex, Ceramic, 130 pF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm
Packaging Specifications	

4000

Packaging

Packaging Quantity

T&R, 180mm, Paper Tape

Specifications	
Capacitance	130 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	2%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute -	- and
we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who hav	ve the
requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by	by us
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